PCN Number:		202	20240306005.1		5.1	PCN Da	ite:	e: March 06, 2024	
Title: Datasheet for LMC555									
Customer Contact: Cha			nge Management			Dep	t:	Quality Services	
Proposed 1st Ship Date:			June 6, 2024						
Change Type:									
Assembly Site				Design			Wafer Bump Site		
Assembly Process			\boxtimes	□ Data Sheet			Wafer Bump Material		
Assembly Materials			Part number change			Wafer Bump Process			
Mechanical Specification			Test Site			Wafer Fab Site			
Pac	Packing/Shipping/Labeling				Test Process			Wafer Fab Materials	
					·		Wafer	Fab Process	
Notification Details									

Notification Details

Description of Change:

TEXAS

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below.

.4	Instruments	NASS58N - JANUARY 2000 - REVISED MARCH 2024
Cha	anges from Revision M (July 2016) to Revision N (March 2024)	Page
•	Updated the numbering format for tables, figures, and cross-references	throughout the document1
•	Updated wording of Features bullets for clarity	
•	Updated GROUND and V+ pin types in Pin Configuration and Function	s3
	Changed V _{CC} to V+ in Pin Configuration and Functions	
•	Added (V+) to DISCHARGE description in Pin Configuration and Func-	tions3
•	Updated R _{BJA} and added detailed thermal characteristics for all package	es in Thermal Information4
•	Moved timing accuracy, timing shift with supply, timing shift with tempe	rature, astable frequency, maximum
1	frequency, output rise and fall times, and trigger propagation delay para	ameters from Electrical Characteristics
1	to Switching Characteristics	5
• (Changed supply current (Is) typical values from 50 µA to 130 µA at Vs	= 1.5 V; from 100 μA to 180 μA at V _S =
	1.5 V; and from 150 μA to 220 μA at V _S = 12 V, in Electrical Characteri	stics 5
• (Changed supply current (I _S) max value from 150 μA to 200 μA at V _S =	1.5 V in Electrical Characteristics5
• (Changed reset current (IRES) test condition to VRES = VS in Electrical C	haracteristics5
•	Added new reset current (I _{RES}) typical value for test condition V _{RES} = 0	V to Electrical Characteristics 5
•	Updated Switching Characteristics to clarify that values are specified b	y design, characterization, or both5
• (Changed units of timing shift with temperature from %V to %/V (typo) is	Switching Characteristics5
• (Changed functional block diagram to simplified schematic and moved to	o Overview7

The datasheet number will be changing.

I MC555

Device Family	Change From:	Change To:
LMC555	SNAS558M	SNAS558N

These changes may be reviewed at the datasheet links provided.

http://www.ti.com/product/LMC555

Reason for Change:

This particular PCN is related to TI's multiyear transition plan for our two remaining factories with 150-millimeter production (DFAB in Dallas, Texas, and SFAB in Sherman, Texas). DFAB will remain open, but will focus on 200-mm production, with a smaller set of technologies. SFAB will close no earlier than 2024 and no later than 2025. As referenced in the "reason for change" below, these changes are part of our multiyear plan to transition these products to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

Electrical specification performance changes as indicated above.

Changes to product identification resulting from this PCN:

None.

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Troduct Arected								
LMC555CMM/NOPB	LMC555CMMX/NOPB	LMC555CMX/NOPB	LMC555CN/NOPB					
LMC555CTP/NOPB	LMC555CTPX/NOPB	LMC555IMX/NOPB						

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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